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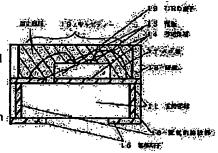
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(54) LED PACKAGE

(57) Abstract:

PROBLEM TO BE SOLVED: To enable an LED device to deteriorate less in emission output and to be increased in mounting reliability when it is mounted on a feeder circuit board, by soldering by a method wherein the light emission peak of the LED device is set lower in wavelength than a specific value, the surface of a dielectric layer is covered with a silver-while precious metal, and the surface of an electrode terminal is coated with Au.

SOLUTION: A conductor layer 14 which feeds an electric power to the electrode 13 of an LED device 12 is formed on the surface of a support member 11, and an electrode terminal 15 where an electric power is fed from an external feeder circuit board is provided to the rear of the support member 11 and connected to the conductor layer 14 with an electrical connector 16. The surface of the conductor layer 14 is coated with silverwhite precious metal, and the surface of the electrode terminal 15 is covered with Au. The emission light peak



of the LED device 12 is set shorter than 600nm in wavelength. By this setup, light emitted from an LED device of emission peak wavelength 600nm can be reflected, and the LED device which is soldered high in strength to a feeder circuit board and high in efficiency and output power can be obtained.

LEGAL STATUS

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